



### Description

- ★ Advanced Trench MOS Technology
- ★ Green Device Available

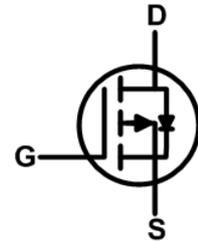
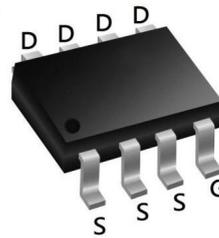
### Product Summary

BVDSS	RDSON	ID
-150V	650mΩ	-1.6A

### Applications

- ★ Load Switch.
- ★ Power Management.
- ★ LED Backlighting.
- ★ Networking application.

### SOP8 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $-V_{GS}$ @ $-10V^1$	-1.6	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $-V_{GS}$ @ $-10V^1$	-0.88	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-4.4	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	12.5	mJ
$I_{AS}$	Avalanche Current	5	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	40	$^\circ C/W$

### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-150	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-1A	---	650	780	mΩ
		V <sub>GS</sub> =-6V, I <sub>D</sub> =-0.5A	---	700	980	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-2.0	-3.0	-4.0	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-120V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =-120V, V <sub>GS</sub> =0V, T <sub>J</sub> =85°C	---	---	30	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	12	---	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-75V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-1A	---	10.8	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.1	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	2.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =-30V, V <sub>GS</sub> =-10V, R <sub>G</sub> =6Ω, I <sub>D</sub> =-1A	---	21	---	ns
T <sub>r</sub>	Rise Time		---	16	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	40	---	
T <sub>f</sub>	Fall Time		---	18	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-75V, V <sub>GS</sub> =0V, f=1MHz	---	706	---	pF
C <sub>oss</sub>	Output Capacitance		---	23	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	13	---	

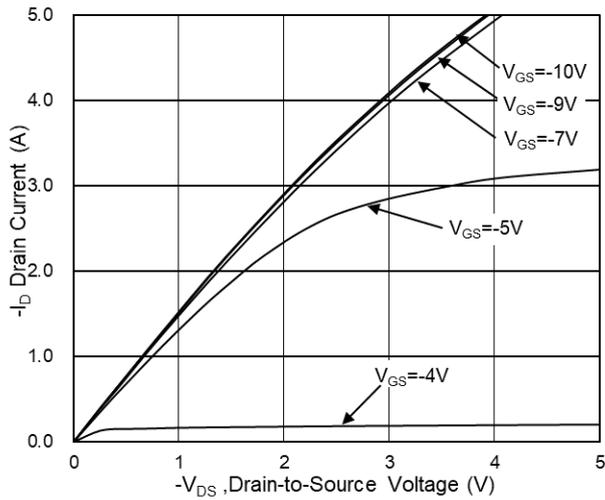
### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-1.6	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1.2	V

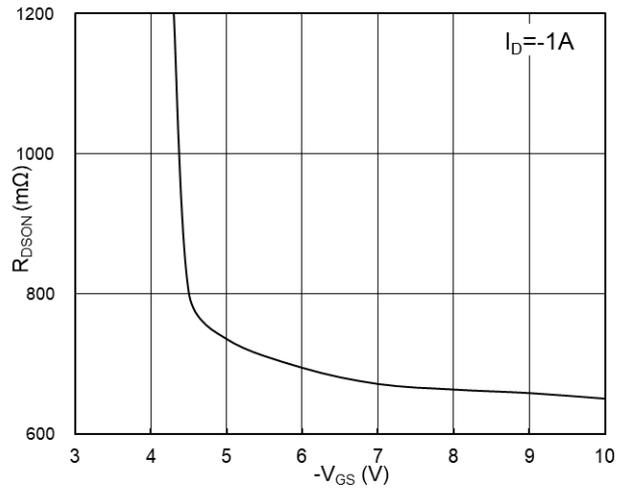
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-50V,V<sub>GS</sub>=-10V,L=1mH,I<sub>AS</sub>=-5A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

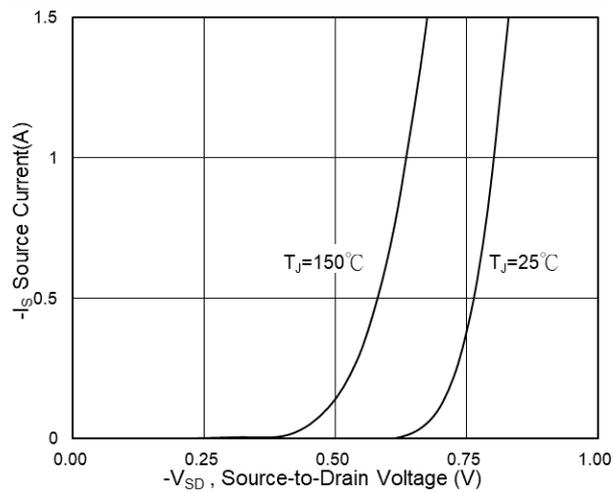
### Typical Characteristics



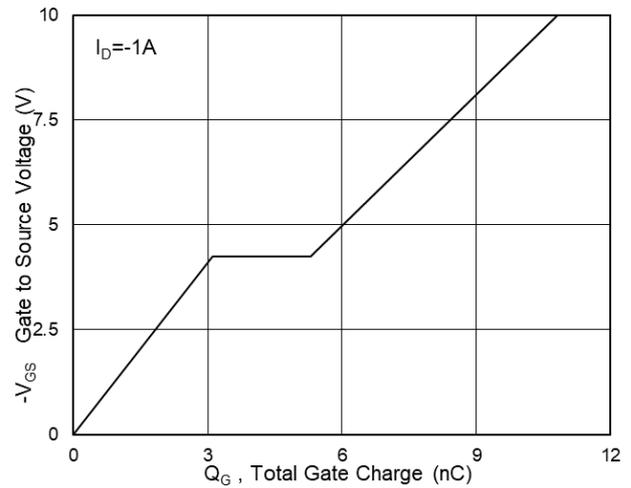
**Fig.1 Typical Output Characteristics**



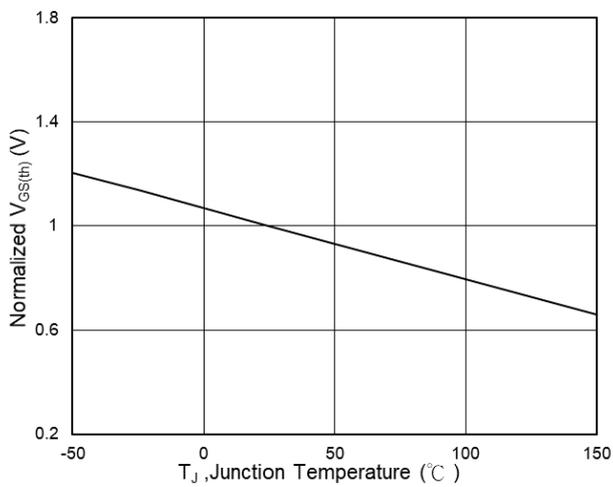
**Fig.2 On-Resistance vs G-S Voltage**



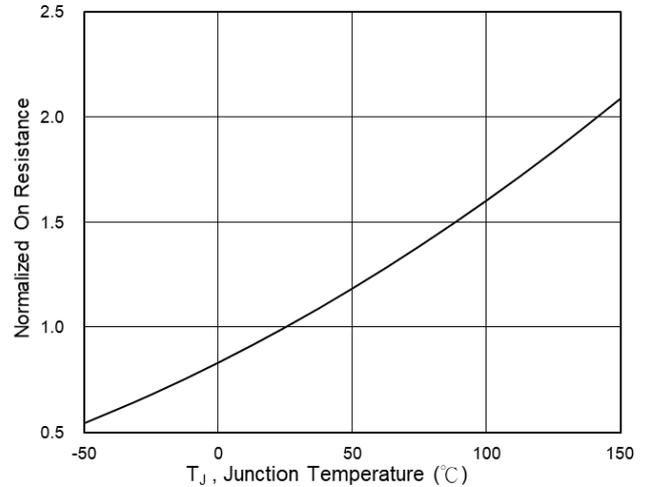
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**

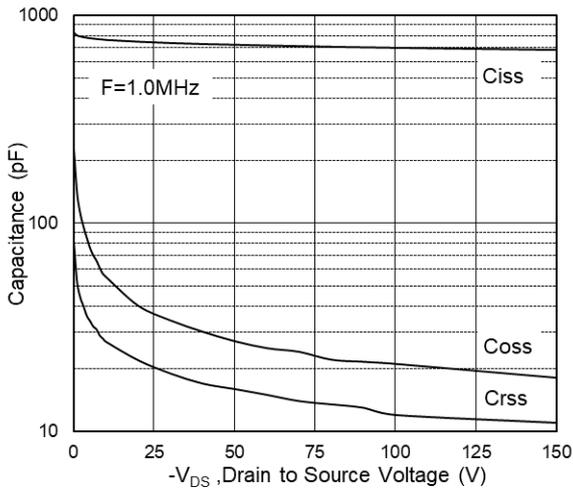


**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$**

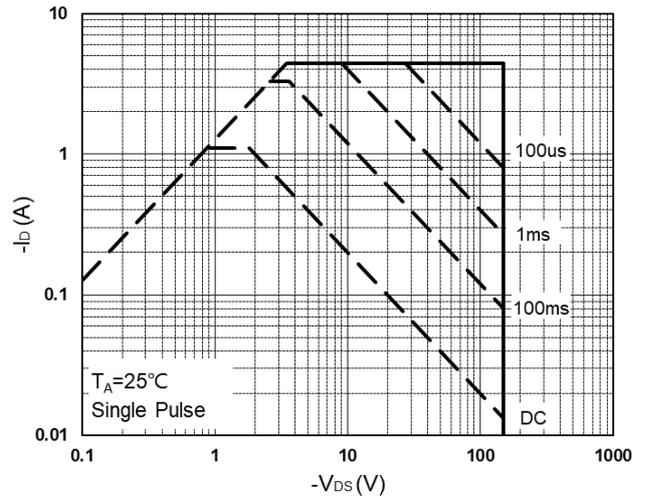


**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**

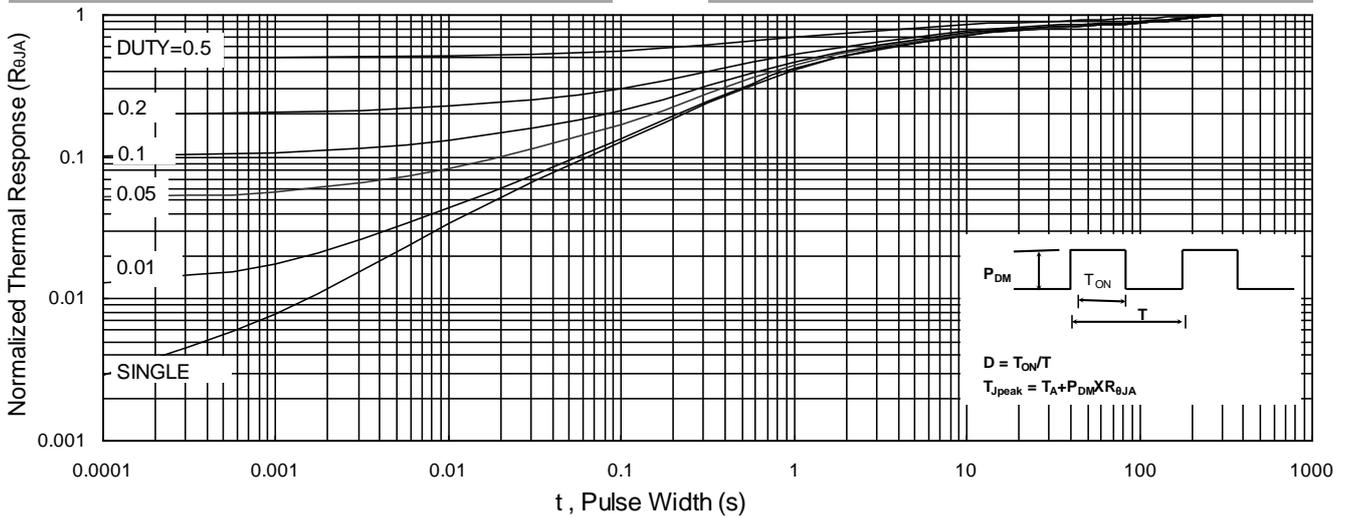
## P-Ch 150V Fast Switching MOSFETs



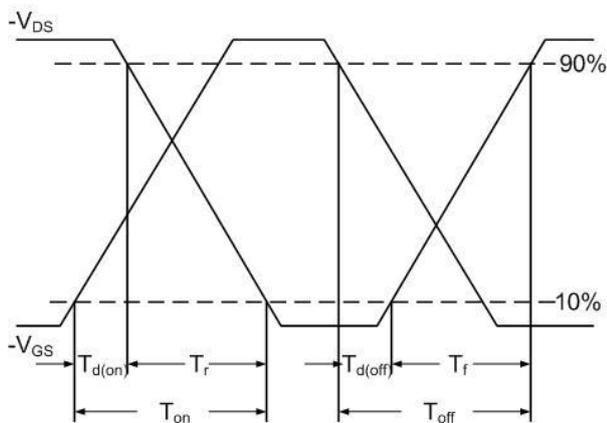
**Fig.7 Capacitance**



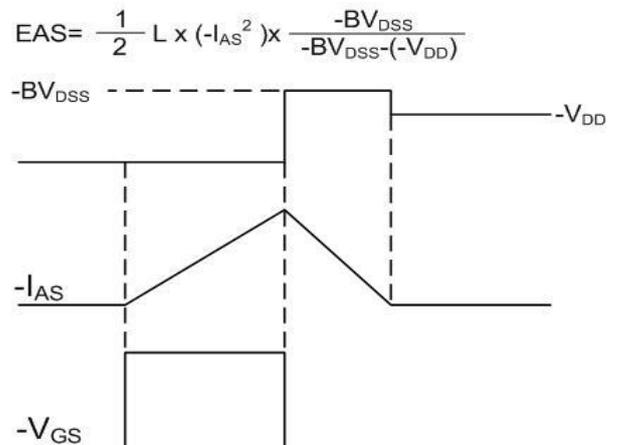
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



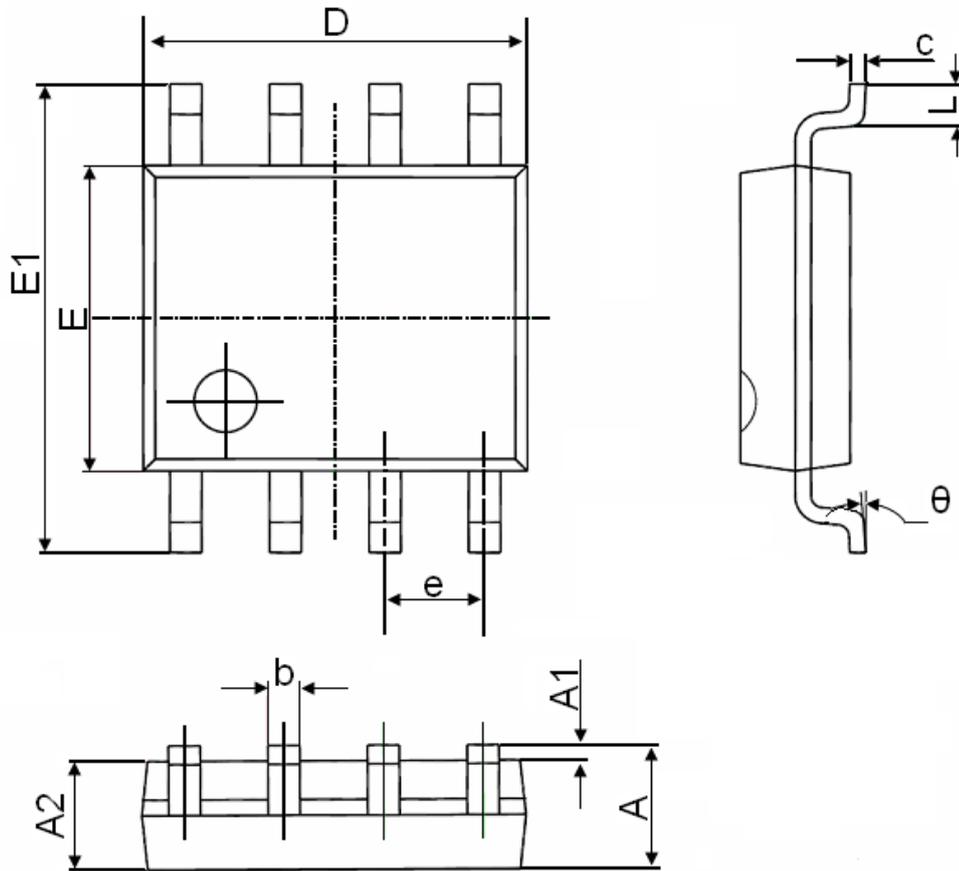
**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**

$$EAS = \frac{1}{2} L \times (-I_{AS}^2) \times \frac{-BV_{DSS}}{-BV_{DSS} - (-V_{DD})}$$

### SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°